Rev. 1.2, 19.12.2018

SMB1N-D450-02

- Blue High Power LED
- 450 nm, 480 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 5.5 mm
- Viewing Angle: 22°





Description

SMB1N-D450-02 is a surface mount InGaN High Power LED with a typical peak wavelength of **450 nm** and radiation of **480mW**. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

Maximum Ratings (TCASE=25°C)

5		Val	11.24		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	P_D		1400	mW	
Forward Current	IF		350	mA	
Pulse Forward Current *1	I FP		700	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	RTHJA		10	K/W	
Junction Temperature	TJ		120	°C	
Operating Temperature	TCASE	- 40	+ 100	°C	
Storage Temperature	T _{STG}	- 40	+ 100	°C	
Lead Solder Temperature *2	T _{SLD}		+ 250	°C	

^{*1} duty=1%, pulse width = 10 µs

Electro-Optical Characteristics (TCASE=25°C)

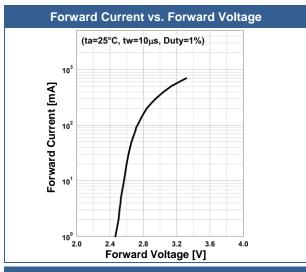
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =350mA	440		460	nm
Dominant Wavelength	λ_D	I _F =350mA		455		nm
Half Width	$\Delta \lambda$	I _F =350mA		20		nm
Forward Voltage	VF	I _F =350mA		3.0	4.0	V
	V_{FP}	I _{FP} =700mA		3.3		
Radiated Power *1	Po	I _F =350mA		480		mW
		I _{FP} =700mA		870		
Radiant Intensity *2	lE	I _F =350mA		1200		mW/sr
		I _{FP} =700mA		2100		
Luminous Flux	I_V	I _F =350mA		22		lm
Viewing Angle	φ	I _F =100mA		22		deg.
Rise Time	t_R	I _F =350mA		40		ns
Fall Time	t⊧	I _F =350mA		80		ns

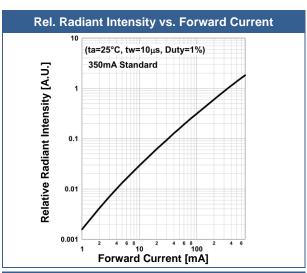
^{*1} measured by \$3584-08

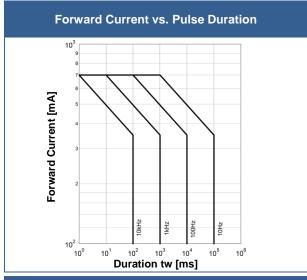
^{*2} must be completed within 5 seconds

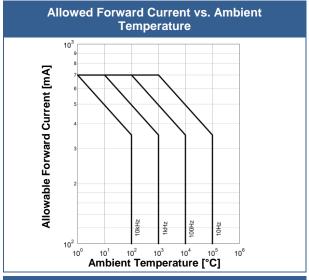
^{*2} measured by CIE127-2007 Condition B

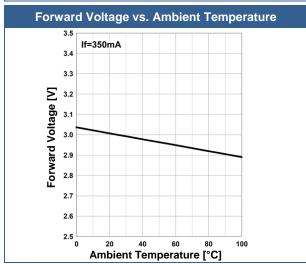
Typical Performance Curves

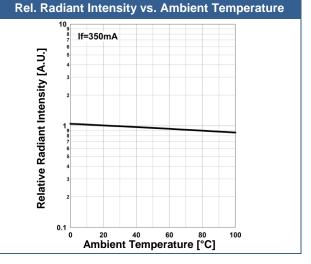










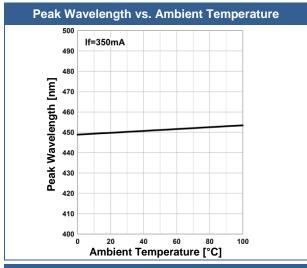


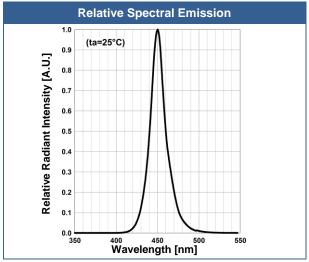


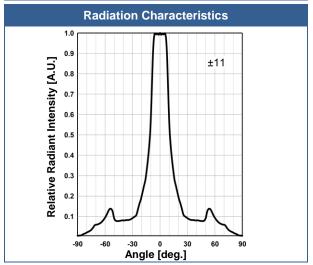
ROITHNER LASERTECHNIK GmbH

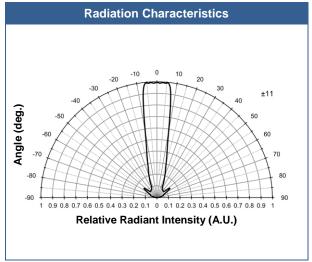
WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM



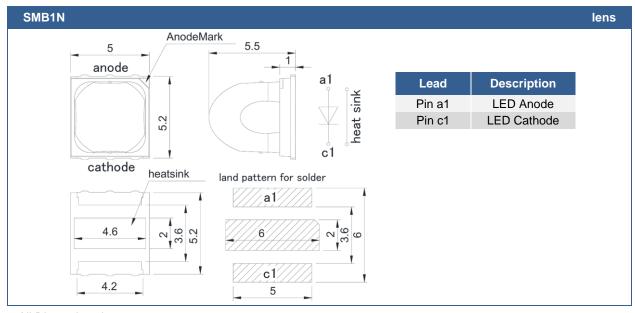








Outline Dimensions



All Dimensions in mm

Precautions

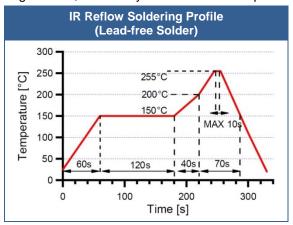
Soldering:

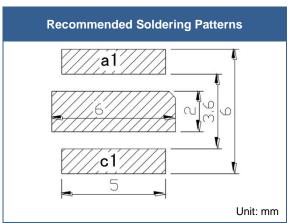
- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

The above specifications are for reference purpose only and subjected to change without prior notice

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